

# DDR4 DIMM Sockets, Halogen-free

*Angled, Ultra Low-Profile, Aerodynamic and Standard versions*



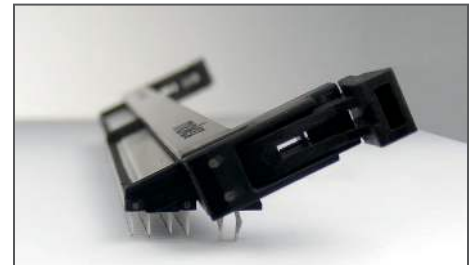
**Angled, Ultra Low-profile, Aerodynamic and Standard DDR4 DIMM sockets combine excellent performance with maximum space-savings and assembly processing for high-speed data and networking applications**

## Features and Benefits

25° angle inclination to the horizontal (Angled version)	Gives up to 45% vertical space savings over Standard vertical versions
Ultra-low seating plane of 1.10mm (Ultra low-profile version)	Frees up vertical module space to allow use of high-density DIMMs while maintaining the same design height; Enables the use of very low-profile modules with seating heights below 2.80mm (maximum) in ATCA* blade systems
Lower current of 0.75A per terminal compared to 1.0A for ULP DDR3 DIMM versions	For bigger energy cost savings
Streamlined housing and latch design (Aerodynamic series)	Minimizes trapping of hot air around high-density memory modules during operation
Metal-reinforced latch tower housing (Angled, Aerodynamic and Standard series)	Prevents cleavage or separation of tower bridge due to wear and tear
Multiple soldertail length options available for Through-hole and Press-fit sockets (Aerodynamic and Standard series)	To suit various PCB thicknesses
Flush soldertail design for SMT socket (Standard series only)	Minimizes accidental damage to terminals due to bending
Anti-stubbing mating contacts (All series)	Provide smooth module lead-in and contact grip during insertion



From left: Standard, Aerodynamic and Ultra Low-Profile DDR4 DIMM Sockets



25°-Angled DDR4 DIMM Socket

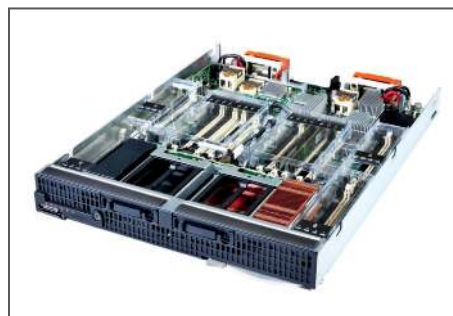
## Applications

### Data/Computing

- High-end computing
- Personal computers
- RAID / Storage

### Telecommunications/Networking

- Infrastructure
- Networking



Servers



Data Centers

# Product Name

Product Description, or series list



## Specifications

### Reference Information

Packaging: Tray  
UL File No.: E29179 (78860)  
CSA File No.: TBA  
Use With: JEDEC MO-309 memory modules  
Designed In: Millimeter  
RoHS: Yes  
Halogen Free: Yes  
Glow Wire Compliant: No

### Electrical

Voltage (max.): 29V AC (RMS)/DC  
Current (max.): 0.75A per pin  
Low Level Contact Resistance (max.):  
12 (78860); 20 (151080); 10 milliohms (others)  
Dielectric Withstanding Voltage: 500V AC  
Insulation Resistance (min.): 1 megohm

### Mechanical

Module Insertion Force (with latches): 106.8N max  
Module Rip-out Force (min.): 9.10kgf  
Compliant-pin Insertion Force to PCB (single):  
4.50kgf max.(78731, 151024)  
Compliant-pin Retention Force to PCB (single):  
0.30kg min. (78731, 151024)  
Module Unmating Force: 2.02kgf  
Terminal Retention Force (min.):  
300gf (per pin);  
13.3N (per forklock for 78860, 151016 only)  
Latch Actuation Force (max.): 3.50kgf per latch  
Durability: 25 cycles

### Physical

Housing: Halogen-free, high-temperature Nylon,  
glass-filled, UL94V-0 (both socket and latch)  
Contact: Copper Alloy  
Plating: Refer to Sales Drawing  
PCB Thickness: Refer to Sales Drawings  
Operating Temperature: -55 to +85°C

## Ordering Information

Series No.	Style	Termination
<a href="#">151080</a>	Angled 25°	Through-hole
<a href="#">78860</a>	Ultra Low-Profile	Through-hole
<a href="#">151016</a>	Aerodynamic	Through-hole
<a href="#">151024</a>		Press-fit
<a href="#">78726</a>	Standard	Through-hole
<a href="#">78730</a>		SMT
<a href="#">78731</a>		Press-fit

[www.molex.com/link/ddr4.html](http://www.molex.com/link/ddr4.html)